



PRODUCT DATA SHEET



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Datasheet

Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

ESD Protection Diode

Features

- 100Watts peak pulse power (tp = 820μ s)
- SOD523 package
- Bidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance (Cj=0.35pF typ.)
- Protection one data/power line to:
- IEC 61000-4-2 \pm 20kV contact \pm 25kV air
- IEC 61000-4-4 (EFT) 40A (5/50ns)
- IEC 61000-4-5 (Lightning) 4.5A (8/20μs)



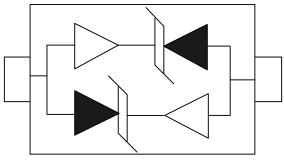
Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation

Mechanical Data

- SOD523 package
- Molding compound flammability rating: UL 94V-0
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

Schematic & PIN Configuration



SOD-523



Absolute Maximum Rating

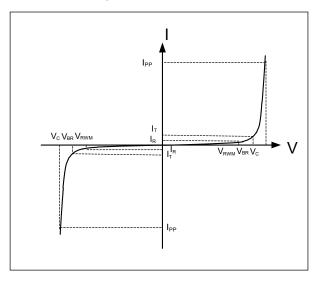
Rating	Symbol	Value	Units
Peak Pulse Power (t _p =8/20μs)	P _{PP}	100	Watts
Peak Pulse Current (t _p =8/20μs) (note1)	I_{pp}	4.5	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	$ m V_{ESD}$	25 20	kV
Lead Soldering Temperature	T_{L}	260(10seconds)	$^{\circ}\!$
Junction Temperature	T_{J}	-55 to + 125	$^{\circ}$ C
Storage Temperature	$T_{ m stg}$	-55 to + 125	$^{\circ}\!$

Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				5.0	V
Reverse Breakdown Voltage	V_{BR}	I _T =1mA	6.0			V
Reverse Leakage Current	I_R	V _{RWM} =5V,T=25°C			0.5	μΑ
Peak Pulse Current	I_{pp}	tp =8/20μs			4.5	A
Clamping Voltage	$V_{\rm C}$	$I_{PP}=4.5A, t_p=8/20 \mu s$			25	V
Junction Capacitance	C_{j}	$V_R = 0V, f = 1MHz$		0.35		pF

Electrical Parameters (TA = 25°C unless otherwise noted)

Symbol	Parameter	
\mathbf{I}_{PP}	Maximum Reverse Peak Pulse Current	
Vc	Clamping Voltage @ IPP	
V _{RWM}	Working Peak Reverse Voltage	
Ir	Maximum Reverse Leakage Current @ VRWM	
V_{BR}	Breakdown Voltage @ IT	
Iτ	Test Current	



Note:. $8/20\mu s$ pulse waveform.



Typical Characteristics

Figure 1: Peak Pulse Power vs. Pulse Time

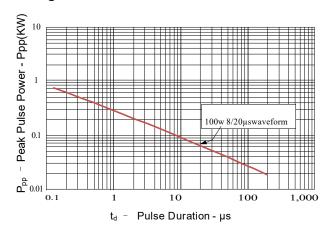


Figure 2: Power Derating Curve

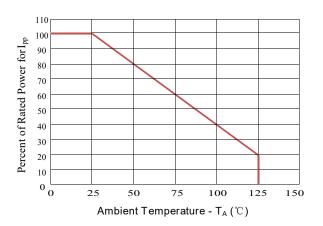


Figure3: Pulse Waveform

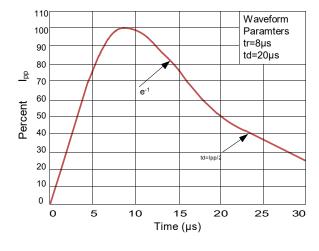
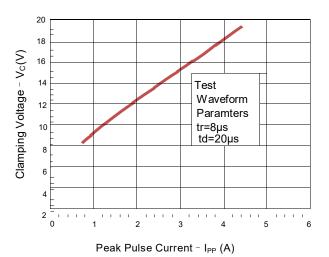
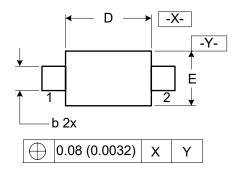


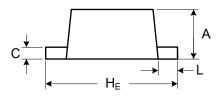
Figure 4: Clamping Voltage vs.lpp





Outline Drawing - SOD523





DIMENSIONS

SYMBOL	MILLIMETER		INCHES		
	MIN	MAX	MIN	MAX	
А	0.50	0.70	0.020	0.028	
b	0.25	0.35	0.010	0.014	
С	0.07	0.20	0.0028	0.0079	
D	1.10	1.30	0.043	0.051	
E	0.70	0.90	0.028	0.035	
H _E	1.50	1.70	0.059	0.067	
L	0.15	0.25	0.006	0.010	



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